0 to 0.1

Each lead has same dimensions

# DC-DC Converter (-20V, -1.0A)

## RTF010P02

#### Features

- 1) Low on-resistance. ( $80m\Omega$  at 2.5V)
- 2) High power package.
- 3) High speed switching.
- 4) Low voltage drive. (2.5V)

### Applications

DC-DC converter

#### ●Structure

Silicon P-channel MOS FET

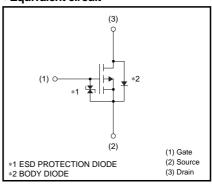
#### Packaging specifications

	Package	Taping	
Type	Code	TR	
	Basic ordering unit (pieces)	3000	
RTF010P02	0		

#### ●Equivalent circuit

TUMT3

●External dimensions (Unit: mm)



Abbreviated symbol : WQ

#### ●Absolute maximum ratings (Ta=25°C)

Parameter		Symbol	Limits	Unit	
Drain-source voltage		VDSS	-20	V	
Gate-source voltage		Vgss	±12	V	
Drain current	Continuous	lσ	±1	Α	
	Pulsed	IDP *1	±4	Α	
Source current	Continuous	Is *1	-0.4	Α	
(Body diode)	Pulsed	Isp	-4	Α	
Total power dissipation		P <sub>D</sub> *2	0.8	W	
Channel temperature		Tch	150	°C	
Range of Storage temperature		Tstg	-55 to +150	°C	
Range of Storage temperature		ıstg	-55 to +150	ů	

<sup>\*1</sup> Pw≤10μs, Duty cycle≤1% \*2 Mounted on a ceramic board

#### ●Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Gate-source leakage	I <sub>GSS</sub>	-	-	±10	μΑ	V <sub>GS</sub> =±12V, V <sub>DS</sub> =0V
Drain-source breakdown voltage	V <sub>(BR)</sub> DSS	-20	-	_	٧	I <sub>D</sub> = -1mA, V <sub>GS</sub> =0V
Zero gate voltage drain current	IDSS	_	_	-1	μΑ	Vps= -20V, Vgs=0V
Gate threshold voltage	VGS (th)	-0.7	_	-2.0	V	V <sub>DS</sub> = -10V, I <sub>D</sub> = -1mA
Static drain-source on-state resistance	R <sub>DS (on)</sub>	_	280	390	mΩ	I <sub>D</sub> = -1A, V <sub>G</sub> S= -4.5V
		_	310	430	mΩ	I <sub>D</sub> = -1A, V <sub>G</sub> S= -4V
		_	570	800	mΩ	I <sub>D</sub> = -0.5A, V <sub>G</sub> S= -2.5V
Forward transfer admittance	Y <sub>fs</sub> *	0.7	-	_	S	V <sub>DS</sub> = -10V, I <sub>D</sub> = -0.5A
Input capacitance	Ciss	-	150	_	pF	V <sub>DS</sub> = -10V
Output capacitance	Coss	-	20	_	pF	V <sub>GS</sub> =0V
Reverse transfer capacitance	Crss	-	20	_	pF	f=1MHz
Turn-on delay time	<b>t</b> d (on) *	_	9	_	ns	ID= -0.5A
Rise time	tr *	_	8	_	ns	VDD≒ -15V
Turn-off delay time	t <sub>d (off)</sub> *	_	25	_	ns	V <sub>GS</sub> = -4.5V R <sub>L</sub> =30Ω
Fall time	t <sub>f</sub> *	_	10	_	ns	RGs= $10\Omega$
Total gate charge	Qg	_	2.1	_	nC	V <sub>DD</sub> ≒−15V RL≒15Ω
Gate-source charge	Qgs	_	0.5	_	nC	$V_{GS}=-4.5V$ RGS= $10\Omega$
Gate-drain charge	Q <sub>gd</sub>	_	0.5	_	nC	I <sub>D</sub> = -1A

Body diode characteristics (source-drain characteristics)

Forward voltage	VSD	_	_	-1.2	V	I <sub>S</sub> = -0.4A, V <sub>G</sub> S=0V



#### Electrical characteristic curves

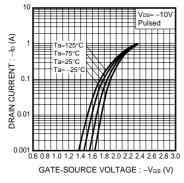


Fig.1 Typical Transfer Characteristics

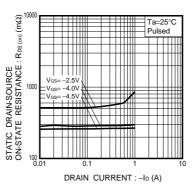


Fig.2 Static Drain-Source On-State Resistance vs. Drain Current

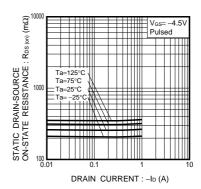


Fig.3 Static Drain-Source On-State Resistance vs. Drain Current

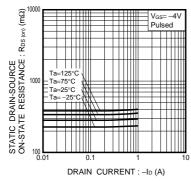


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current

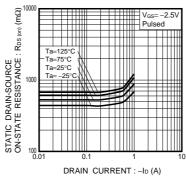


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current

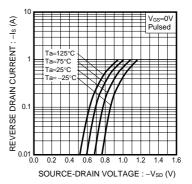


Fig.6 Reverse Drain Current vs. Source-Drain Voltage

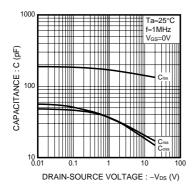


Fig.7 Typical Capacitance vs. Drain-Source Voltage

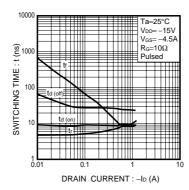


Fig.8 Switching Characteristics

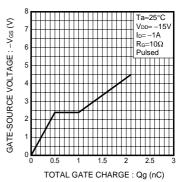


Fig.9 Dynamic Input Characteristics

#### ●Measurement circuits

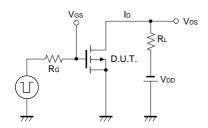


Fig.10 Switching Time Measurement Circuit

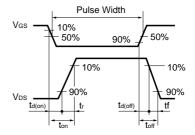


Fig.11 Switching Waveforms

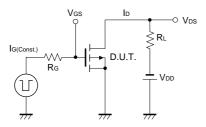


Fig.12 Gate Charge Measurement Circuit

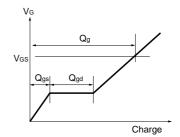


Fig.13 Gate Charge Waveforms

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